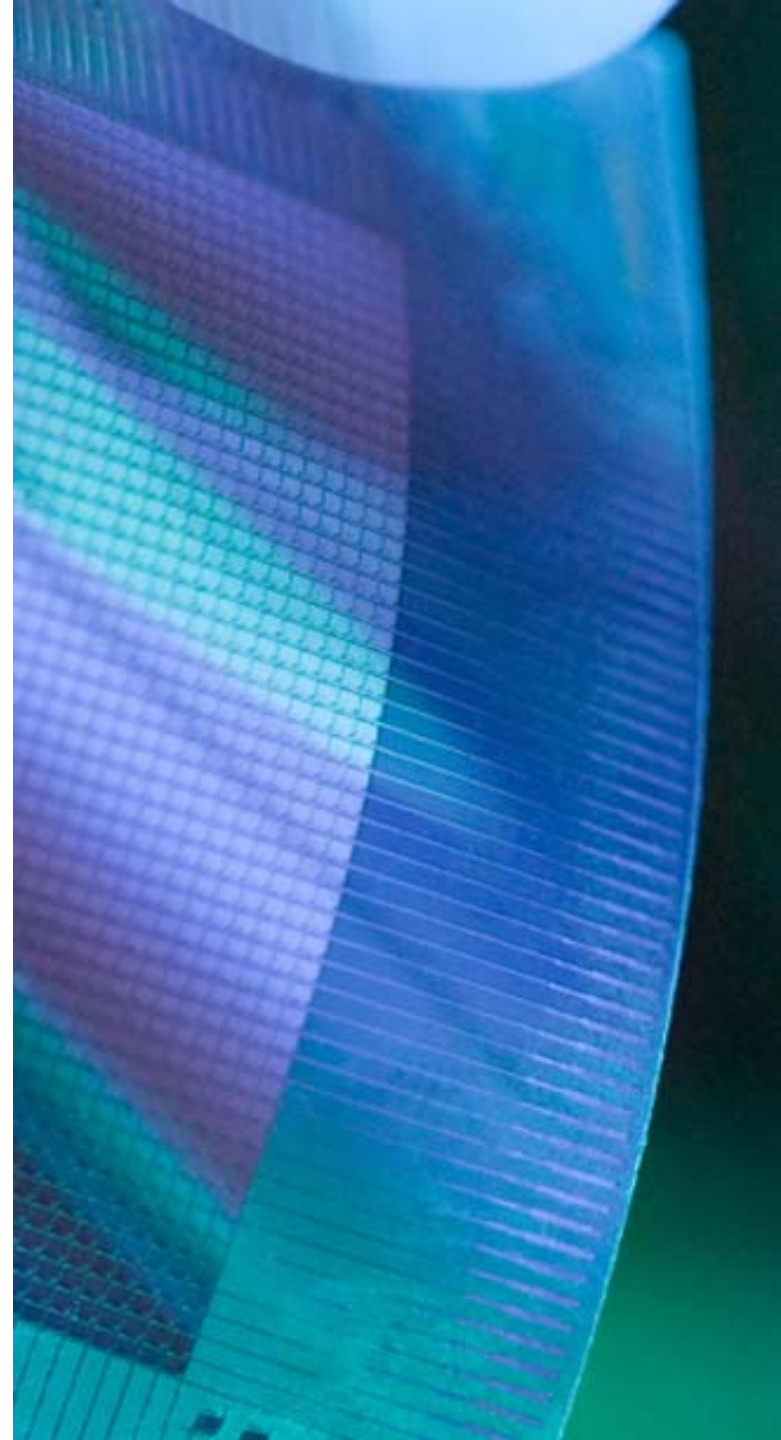


Challenges and opportunities for the flexible electronics industry

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about PARC



Palo Alto Research Center
– incorporated in 2002 (formerly Xerox PARC)

◆ 4 Divisions

- Computer Science
- Intelligent Systems
- Hardware Systems
- Electronic Materials & Devices

Large Area Electronics,
MEMS, Optoelectronics,
Printing Systems,
Biomedical Systems,
Clean Technology, ...

about PARC



Palo Alto Research Center
– incorporated in 2002 (formerly Xerox PARC)

◆ Research as a business

- Research with client companies and the Government
- Partnerships with new ventures
- New business creation
- Licensing and technology transfer

The Vision for Flexible Electronics

- ◆ **There will be new applications that utilize flexibility**
- ◆ **And new applications that benefit from flexibility**
 - Lighter, more robust,.....
 - Lowered cost of manufacturing
 - Custom devices and systems
- ◆ **A destabilizing technology will be created**
 - There are likely to be new winners
 - ▶ Will they be in Asia, Europe or USA?

Applications that need flexibility

◆ Displays

- Placed on curved surfaces, wearable
- Roll-able
- Robust

◆ Photovoltaics

- Placed on curved surfaces
- Aesthetics as well as function

◆ Digital X-ray imagers

- Conformal – surrounding the object
- Robust

◆ Medical devices

- Electronic patch
- Implantables

◆ Systems on a foil

- Wearable devices
- Designed for people, not imposed on them

Benefits to industry from flexible substrates

◆ Roll-roll manufacturing

- Exists in many areas: newspapers, packages.....
- Low cost at high volume

◆ Thin, light substrates

- Ultra-light systems
- Stackable

◆ Robustness

- No brittle devices

◆ Examples

- RFID
- Photovoltaics
- Smart labels
- Lighting
- Smart phones
- Tablets.....

Our perspective:

◆ **Flexible Electronics is an exciting opportunity**

- New technology capabilities
- New business opportunities

◆ **And – it is happening**

- Particularly in Europe

◆ **Applications will drive the technology**

- People want solutions – not technology
- And they want convergence of functions

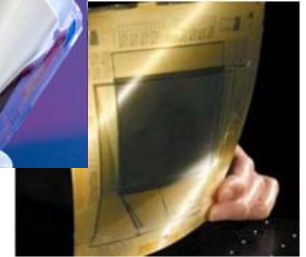
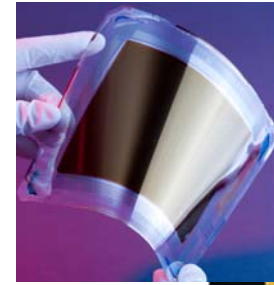
◆ **Challenges**

- Commercial: How can we launch the industry?
- Government: Where is the best leverage?

PARC's approach

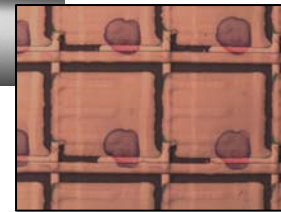
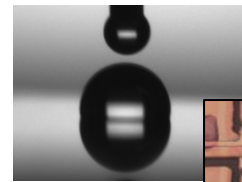
◆ Make “standard” technologies flexible

- Amorphous and poly-crystalline Si



◆ Exploit printing technology

- Inkjet
- Gravure



◆ Develop organic electronics

◆ Demonstrate with applications

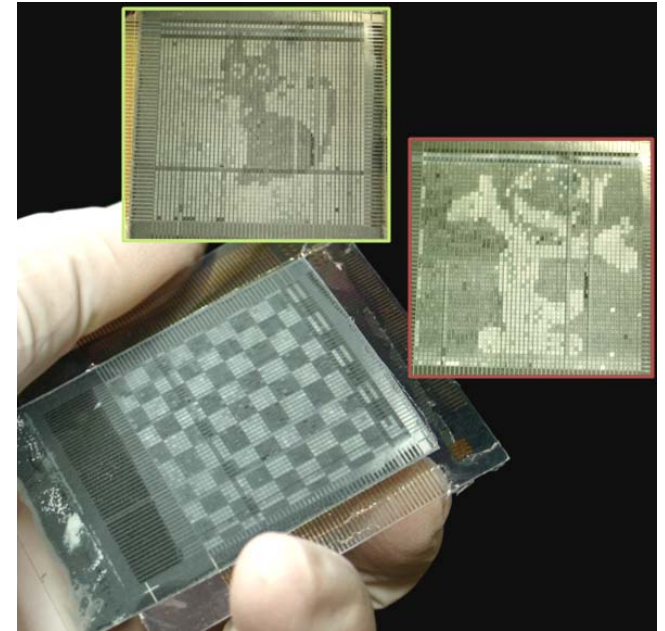
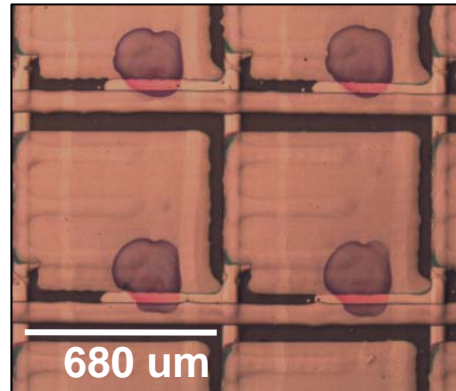
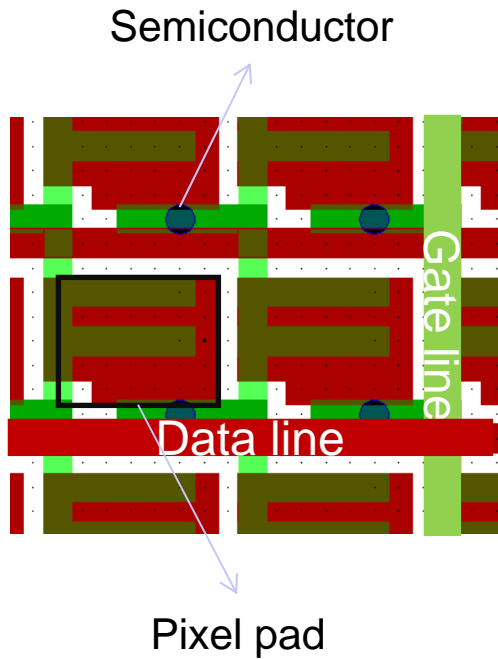
- Displays
- Sensors
- Systems



◆ Develop hybrid approaches



Example 1: All-additive printed arrays



PARC has demonstrated all-printed TFT backplanes for displays

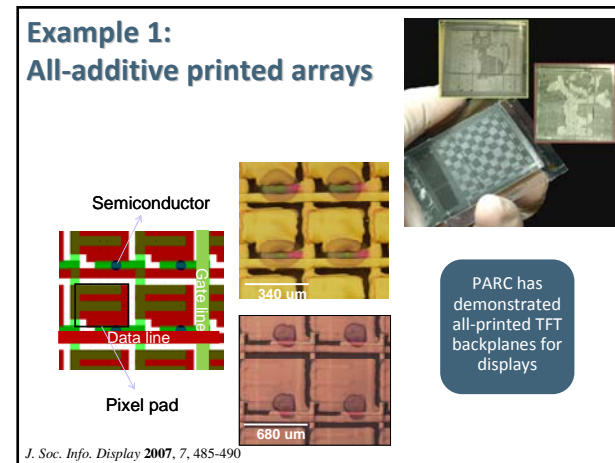
Why this is important

◆ Fewer steps

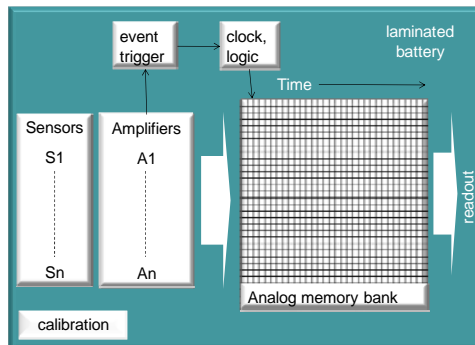
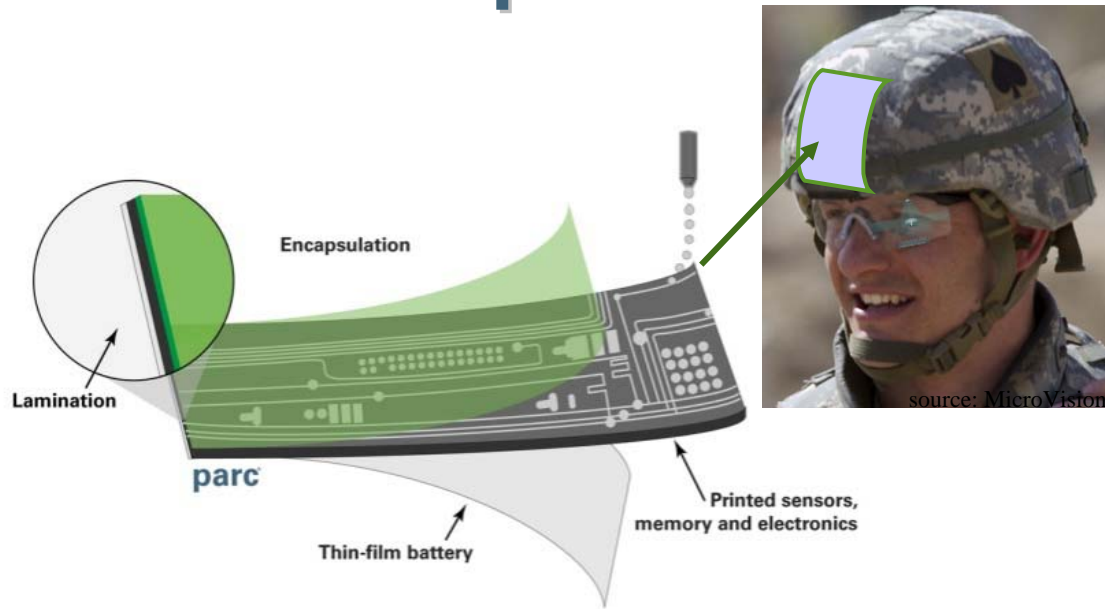
- Printed:
 - ▶ 4 layers = 4 steps
- Traditional:
 - ▶ 4 layers = 16-20 steps

◆ Scalable to simpler applications

- custom applications
- Smart labels etc.



Example 2: Printed Sensor Tape

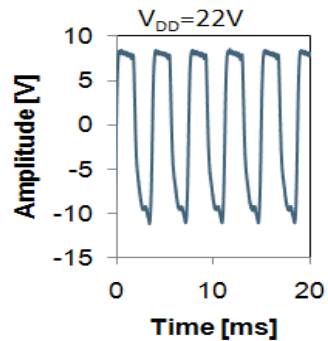
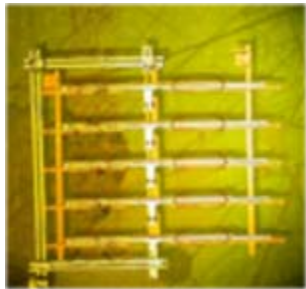


- Monitor pressure, acceleration, sound, light
- Signals recognized, processed, sent to memory
- Non-volatile memory holds data for one week
- Off-board readout system

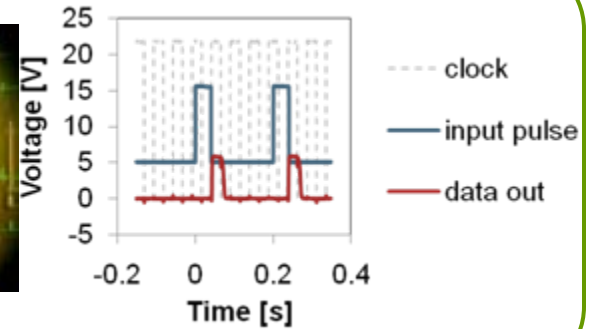
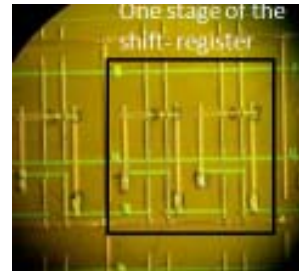
Monitoring environment to prevent traumatic brain injury.
(DARPA)

Sensor Tape: Printed Electronics

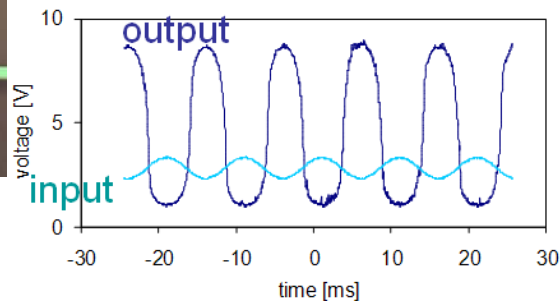
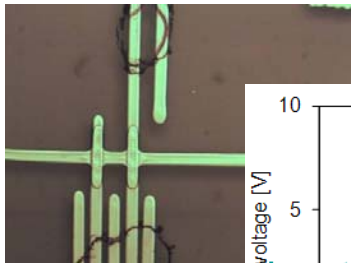
Ring oscillator



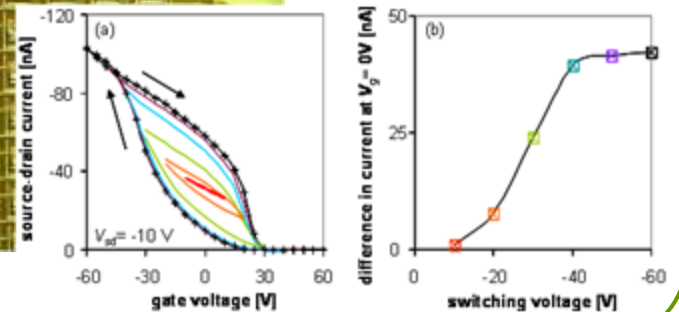
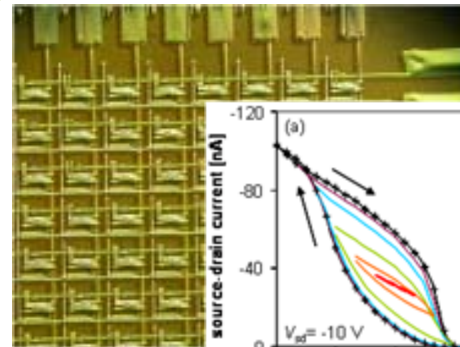
Shift Register



Amplifier

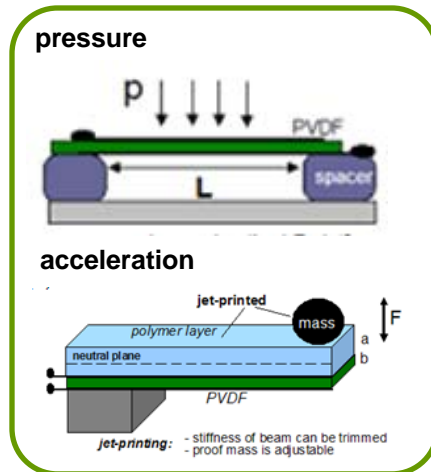


Memory

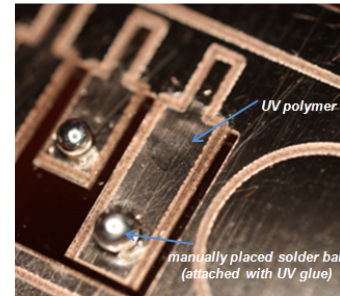


Sensors

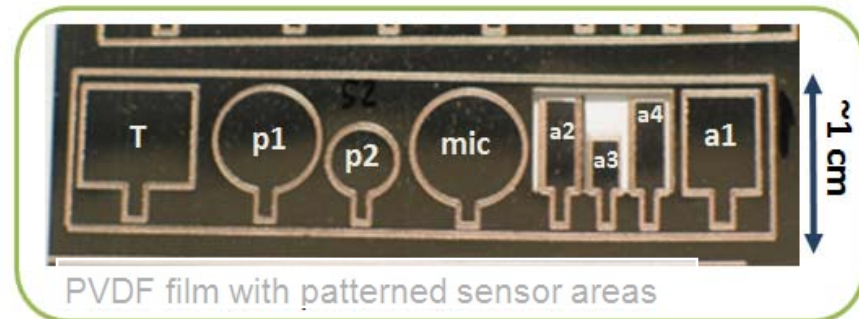
◆ Piezoelectric sensing



Cantilever-based sensors



PVDF cantilever accelerometer structures
(proof mass manually glued to surface)

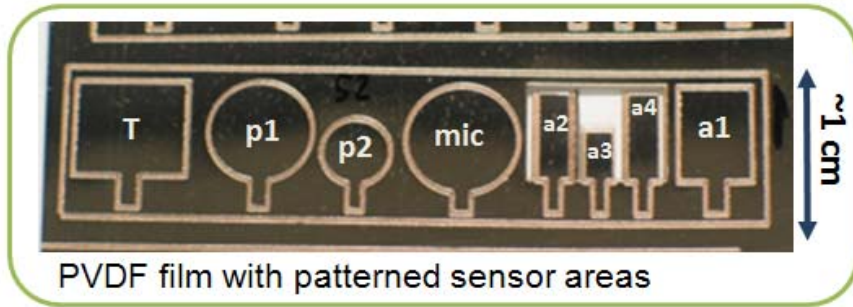


PVDF film with patterned sensor areas

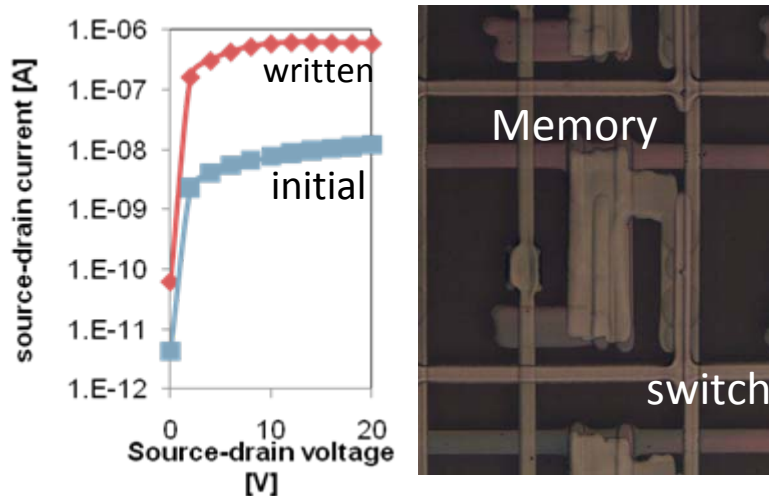
Laminated PVDF foil or PVDF-TrFE solution

Sensor Tape: Next step: integration

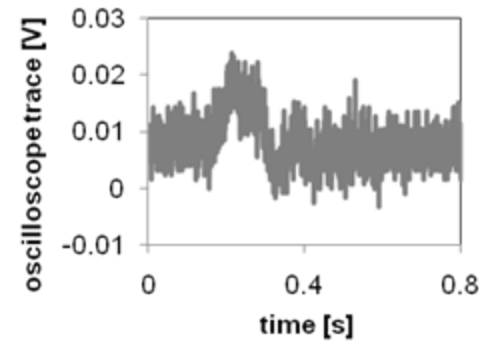
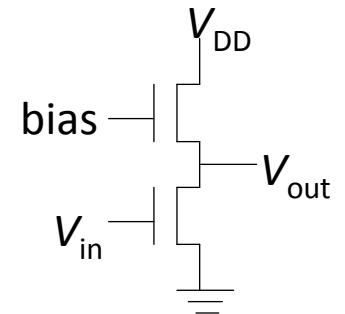
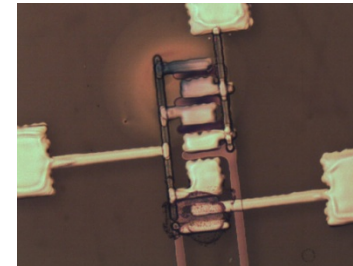
MEMS sensors



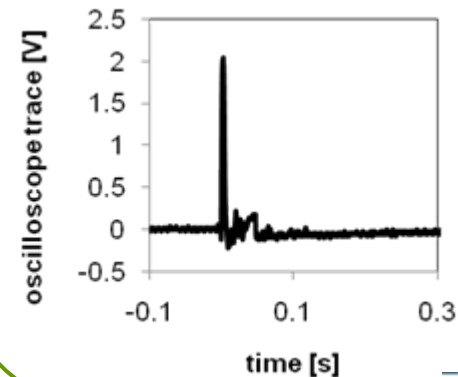
Printed memory cells



Printed organic amplifiers



Pressure signal without amplifier



Pressure signal after amplifier

What we have learned

◆ Flexible sensor systems will be important

◆ Hybrid devices are very promising

- Silicon + organics
- Printed + traditional manufacturing

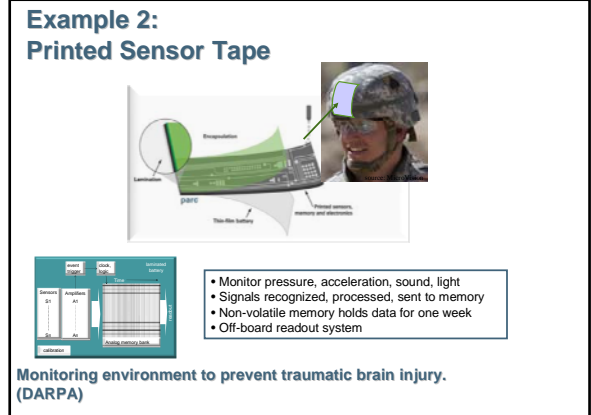
◆ Integration into a system can be done

- but is challenging

◆ Taking this to the next level is difficult

↻ Applications need volume
↻ Volume needs applications

- Does the industry wait for a company with enough money and demand to drive the development of a particular device
AND the industry itself?



PARC's view

- ◆ **The flexible electronics industry has a huge future**
- ◆ **We are active across the industry and work with a wide range of participants**
- ◆ **With our clients and partners, we invent, develop and demonstrate**
 - Processes
 - Prototypes
 - Applications
- ◆ **We are investing in**
 - Components
 - Partnerships for manufacturing

What more is needed?

◆ Focus on development of applications

- There is currently some funding for processes and capabilities
 - ▶ This should be enhanced
- We need to put this together with applications
 - ▶ The big missing piece in the US

◆ This could kick-start the industry

.... the relatively low prevalence of actual manufacturing and advanced systems research and development in the United States has led to an incomplete hybrid flexible electronics R&D scenario for this country..... [NSF/ONR Report: www.wtec.org/flex/]

Thank you

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